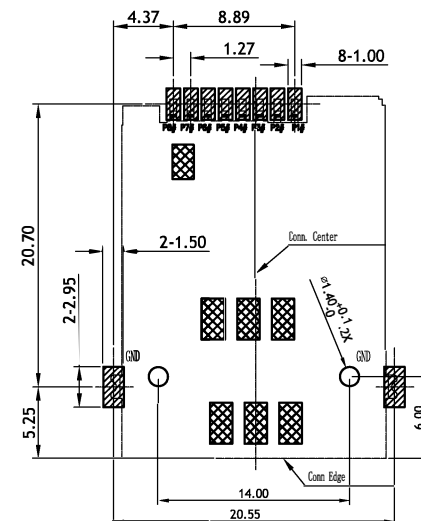
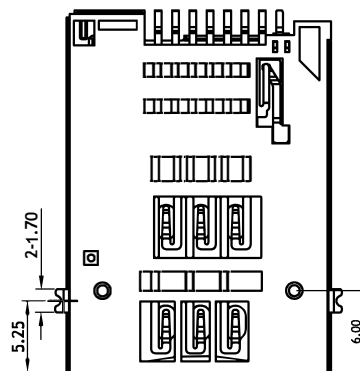
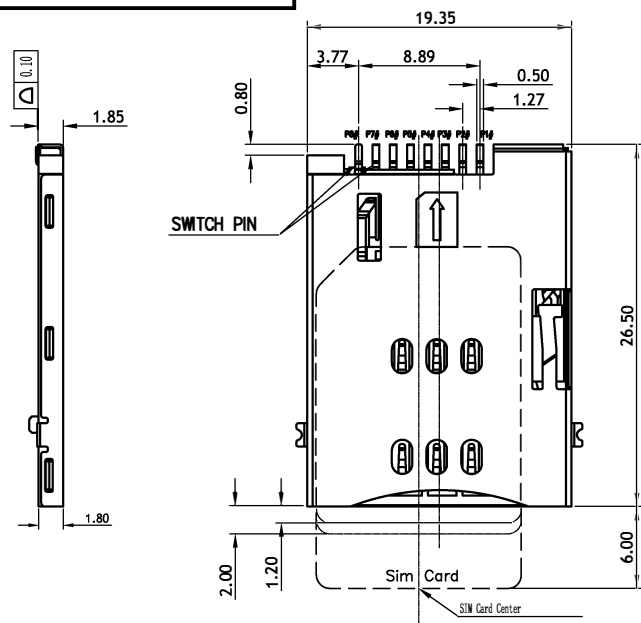


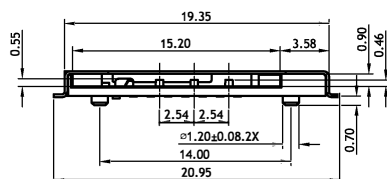
RoHS COMPLIANT



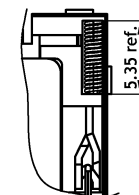
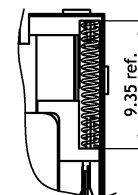
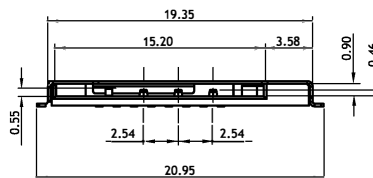
RECOMMENDED PCB LAYOUT (TOP VIEW)
GENERAL TOLERANCES: ±0.05

▨ SOLDER AREA
▩ NONE CIRCUIT DIAGRAM AREA

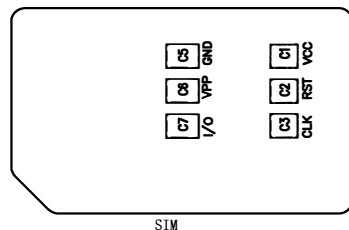
SN-M1806P



SN-M1806



PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET



NOTES:

1. MATERIAL:
HOUSING: LCP UL 94V-0
CONTACT: CS210R-H, T=0.15
SHELL: 9030A, T=0.20
WELAR: POLYESTER
2. FINISH:
CONTACT: GOLD FLASH PLATED Mating Area;
GOLD FLASH PLATING ON SOLDER TAILS, WITH ENTIRE CONTACT UNDERPLATED
SOL: MIN. NICKEL SHELL: 500/min. NICKEL UNDERPLATED OVERALL;
GOLD FLASH PLATED ON SOLDER TAILS
3. INFRARED REFLOW SOLDERING: 10sec. Min. at 260°C
4. ELECTRICAL CHARACTERISTICS:
CURRENT RATING: 0.5A
WITHSTANDING VOLTAGE: AC500V r.m.s
INSULATION RESISTANCE: 1000 Megohms Min. at DC 500V CONTACT
RESISTANCE: 100 Milliohm Max.
5. ENVIRONMENTAL:
OPERATING TEMPERATURE: -40°C TO +60°C
6. MECHANICAL CHARACTERISTICS: DURABILITY: 2000 CYCLES Min.

Part number Information:

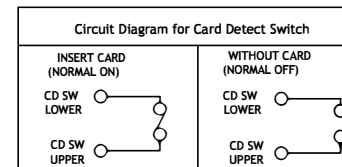
SN-M1806X-XX

"P" - with Peg

"Blank" - without Peg

Terminal area Plating:

blank: Gold Flash Plating Mating Area
03:3u" Gold Plating Mating Area
06:6u" Gold Plating Mating Area
15:15u" Gold Plating Mating Area
30:30u" Gold Plating Mating Area



						Angle	±2°	DESIGN	Aple	2015.05.25		SATRON ELECTRONICS LTD.	
				Aple	Rix	X.X	±0.30	CHECK	Jason	2015.05.25			
				Aple	Rix	X.XX	±0.20	APPROVAL	Rix	2015.05.25		TITLE:	SIM card 6+2 pin push H1.8
	A-0	2015.05.25	NEW	Aple	Rix	X.XXX	±0.10	SCALE: N/A	UNIT: mm	A4	SHEET: 1 of 1	MODEL NO.	SN-M1806X-XX
ECN NO.	REV	DATE	DESCRIPTION	CHANGE	APPRO.	GENERAL TOLERANCE UNLESS OTHERWISE NOTED							